

ABSTRACT

PHOTOSENSITIVE RESIN COMPOSITION

This invention provides a photosensitive resin composition and in particular, it provides a photosensitive resin composition comprising a) an acryl-based copolymer obtained by copolymerizing i) an unsaturated carbonic acid, unsaturated carbonic anhydride or mixture thereof, ii) an epoxy group containing unsaturated compound; iii) an olefin-based unsaturated compound; and iv) a silane-based monomer; b) a 1,2-quinonediazide compound; and c) a solvent.

The photosensitive resin composition according to the invention has not only excellent performances in sensitivity, transmission, insulation, chemistry resistance, flatness, coating and so on but also remarkably improved adhesion especially to inorganic substances so that it is suitable to form interlayer dielectrics during LCD manufacturing process.